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Deborah W. Wenocur
Deborah W. Wenocur

#9/A
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6/25/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Applicant: K. Sahota, D. Schonauer, J. Groschopf,)
G. Marxsen, and S. Avanzino,) Grp Art Unit: 1765
Assignee: Advanced Micro Devices, Inc.) Exam: L. Umez Eronini
Serial Number: 09/749,191)
Filed: December 26, 2000)
For: PREVENTION OF PRECIPITATION)
DEFECTS ON COPPER INTER-)
CONNECTS DURING CMP BY USE)
OF SOLUTIONS CONTAINING)
ORGANIC COMPOUNDS WITH)
SILICA ADSORPTION AND COPPER)
CORROSION INHIBITING)
PROPERTIES)

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Assistant Commissioner for Patents
Washington, D.C. 20231

AMENDMENT AND RESPONSE TO OFFICE ACTION

Dear Sir,

This is in response to the Office Action mailed on February 28, 2002.

The Examiner has made final the restriction requirement to either: slurry composition claims 1-55 and 62, or method claims 56 – 73 and not 62. Applicant affirms the election with traverse of method claims 56 – 73 and not 62.